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Abstract of the Disclosure

[0041] A particle-removing wafer is disclosed which is suitable for removing particles from a wafer support surface such as a wafer chuck used to support semiconductor wafers during the testing of IC devices on the wafers, for example. The particle-removing wafer includes a support body on which is provided a particle-adherent layer having a particle-adherent surface to which particles adhere when the particle-adherent surface is placed into contact with the particles. Consequently, upon subsequent placement of a production wafer on the wafer chuck, particles which may otherwise induce cracking of the wafer are no longer present on the chuck.